



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSC0921NDI	Issued	03. May 2021
MA#	MA001013776		
Package	PG-TISON-8-3	Weight*	101.65 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.210	0.21	0.21	2070	2070
chip_2	inorganic material	silicon	7440-21-3	0.707	0.70	0.70	6951	6951
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		101	
	non noble metal	zinc	7440-66-6	0.041	0.04		404	
	non noble metal	iron	7439-89-6	0.822	0.81		8083	
	non noble metal	copper	7440-50-8	33.360	32.82	33.68	328206	336794
wire	noble metal	gold	7440-57-5	0.068	0.07	0.07	668	668
encapsulation	organic material	carbon black	1333-86-4	0.092	0.09		905	
	plastics	epoxy resin	-	4.740	4.66		46633	
	inorganic material	silicondioxide	60676-86-0	41.187	40.50	45.25	405208	452746
leadfinish	non noble metal	tin	7440-31-5	1.108	1.09	1.09	10900	10900
plating	noble metal	silver	7440-22-4	0.186	0.18	0.18	1828	1828
solder	non noble metal	tin	7440-31-5	0.029	0.03		282	
	noble metal	silver	7440-22-4	0.036	0.04		353	
	non noble metal	lead	7439-92-1	1.370	1.35	1.42	13480	14115
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.01		52	
	non noble metal	zinc	7440-66-6	0.021	0.02		209	
	non noble metal	iron	7439-89-6	0.424	0.42		4174	
	non noble metal	copper	7440-50-8	17.228	16.95	17.40	169493	173928
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com